



We develop, manufacture and qualify on-board thermal links for observation satellites. They physically link the cryogenic cooler to the application to be cooled (focal plane, detector, thermal screen, etc.).

Thermal links are based on a complex process of assembling strips of conductive materials:

- High-purity aluminum
- OFHC copper (high purity)
- POG (Pyrolytic oriented graphite)

Thermal links are used to ensure **high conductive coupling between the coolers** (nominal and redundant) and **the detectors on the optical bench**. Thanks to the flexibility of the straps, they allow the accumulation of a 3-axis static bias (alignment of the detector and dynamic deflections during the flight phase).

The rigorous constraints of the space sector are met thanks to a reduced mass that allows us to remain within the reduced static and dynamic volume of the *Interface Requirement Document.* 

- Very high thermal conductivity
- Reduced mass
- Compact footprint
- Meets space requirements (cleanliness / durability)
- Micro-vibration filtering
- Flexibility
- Mechanical resistance to flight
- Particle and molecular cleanliness (detector proximity)

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Thermal contact zones



Thermal links in oriented pyrolytic graphite



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FCI and IRS	Third-generation Meteosat satellite (MTG)		
IASI-NG instrument	MEtOp SG satellite		
METImage instrument	EUMETSAT polar system satellite		
NISP instrument	EUCLID space mission, mapping the dark universe		
CO2M and LSTM	Copernicus		

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The choice of conductive material for strip assemblies depends on the operating temperature:

	Temperatures	Mass	Flexibility	Cleanliness
Pure Aluminium	10 - 80 K	+	+	+ +
OFHC Copper	<10K	=	=	=
Oriented pyrolitic graphite	> 80 K	+ +	+ +	+

**Cleanliness** is a very important factor given the proximity of the detector: solutions have been developed for the various technologies to ensure cleanliness levels below 50 PPM.

All thermal links manufactured by Absolut System **comply with the cleanliness requirements imposed by the proximity of the detector**, and survive launch loads and thermal cycles without performance degradation.







